

DATASHEET

6 PIN DIP RANDOM-PHASE TRIAC DRIVER PHOTOCOUPLER EL301X, EL302X, EL305X Series



Features:

- Peak breakdown voltage
- 250V: EL301X- 400V: EL302X- 600V: EL305X
- High isolation voltage between input and output (Viso=5000 V rms)
- Compact dual-in-line package
- Pb free
- Compliance with EU REACH
- The product itself will remain within RoHS compliant version
- UL and cUL approved
- VDE approved
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Description

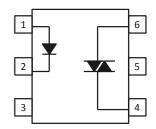
The EL301X, EL302X and EL305X series of devices each consist of an infrared emitting diode optically coupled to a monolithic silicon random phase photo Triac.

They are designed for interfacing between electronic controls and power triacs to control resistive and inductive loads for 115 to 240 VAC operations.

Applications

- Solenoid/valve controls
- Lamp ballasts
- Static AC power switch
- Interfacing microprocessors to 115 to 240Vac peripherals
- Incandescent lamp dimmers
- Temperature controls
- Motor controls

Schematic



Pin Configuration

- 1. Anode
- 2. Cathode
- 3. No Connection
- 4. Terminal-MT2
- 5. Substrate (do not connect)
- 6. Terminal-MT1



Absolute Maximum Ratings (Ta=25°C)

| | Parameter | | Symbol | Rating | Unit |
|-----------|------------------------------------------------|------------|---------------------|-----------------------------|------|
| Input | Forward current | | l _F | 50 | mA |
| | Reverse voltage | | V_{R} | 6 | V |
| | Power dissipation | | P_{D} | 100 | mW |
| Output | | EL301X | | 250 | |
| | Off-state Output Terminal Voltage | EL302X | V _{DRM} | 400 | V |
| | · · · · · · · · · · · · · · · · · · · | EL305X | _ | 600 | |
| | On-State RMS Current | | I _{T(RMS)} | 100 | mA |
| | Peak Repetitive Surge ((pw≤100µs,120pps) | Current | Ітр | 2 | А |
| | Peak Non-repetitive Sur (f=60Hz, one cycle) | ge Current | Ітѕм | 1 | А |
| | Power dissipation | | Po | 300 | mW |
| Total pow | ver dissipation | | P _{TOT} | 400 | mW |
| Isolation | voltage ^{*1} | | V_{ISO} | 5000 | Vrms |
| Operatin | g temperature | | T _{OPR} | -40 to 100 | °C |
| Storage | temperature | | T _{STG} | T _{STG} -55 to 125 | |
| Soldering | Soldering Temperature*2 | | | 260 | °C |

Notes:

Recommended Operating Conditions (Note)

Please use under recommended operating conditions to obtain expected characteristics

| Parameter | Symbol | Min. | Тур. | Max. | Unit | |
|-----------------------|--------|----------------|------|------|------|----|
| | EL30X1 | _ | 20 | 25 | 30 | mA |
| Forward current | EL30X2 | l _F | 15 | 20 | 25 | mA |
| | EL30X3 | | 7 | 10 | 20 | mA |
| AC mains voltage | | V_{AC} | - | - | 240 | V |
| Operating temperature | | Topr | -25 | - | 85 | °C |

Notes:

The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.

^{*1} AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2&3 are shorted together, and pins 4, 5 & 6 are shorted together.

^{*2} For 10 seconds



Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

| Parameter | Symbol | Min. | Typ.*1 | Max. | Unit | Condition |
|-------------------------|----------------|------|--------|------|------|-----------------------|
| Forward Voltage | VF | - | 1.18 | 1.5 | V | I _F = 10mA |
| Reverse Leakage current | I _R | - | - | 10 | μΑ | $V_R = 6V^{*1}$ |

Note:

Output

| Parameter | Symbol | Min. | Typ. *1 | Max. | Unit | Condition |
|-----------------------------------------|------------------|------|---------|------|------|---------------------------------------------------------------------------------|
| Peak Blocking Current | I _{DRM} | - | - | 500 | nA | V _{DRM} = Rated V _{DRM} I _F = 0mA* ² |
| Peak On-state Voltage | V _{ТМ} | - | - | 3.0 | V | I _{T(RMS)} =100mA I _F =Rated I _{FT} |
| Critical Rate of Rise off-state Voltage | dv/dt | 600 | - | - | V/µs | $V_{PEAK} = 0.636 \times Rated V_{DRM}$, $I_F = 0mA (Fig.10)$ |

Notes:

- *1. Typical values at $T_a = 25$ °C.
- *2. Test voltage must be applied within dv/dt rating.

Transfer Characteristics

| Parame | eter | Symbol | Min. | Typ ^{.*1} | Max. | Unit | Condition |
|------------------------|----------------------------|-----------------|------|--------------------|------|------|-------------------------------------------|
| | EL3020 | | | | 30 | | |
| | EL3010 EL3021 EL3051 | | - | - | 15 | | |
| LED Trigger Current | EL3011 EL3022 EL3052 | l _{FT} | - | - | 10 | mA | Main terminal Voltage=3V* ⁴ |
| | EL3012 EL3023 EL3053 | | - | - | 5 | | |
| Holding Curren | t | lΗ | - | 250 | - | μΑ | |

Notes:

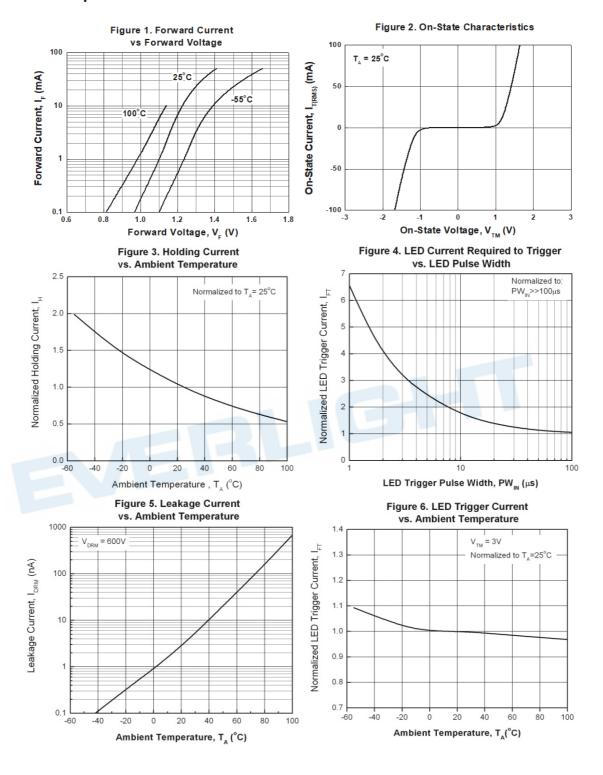
^{*1.}Reverse Voltage(VR) Condition is applied to IR test only. The device is not designed for reverse operation

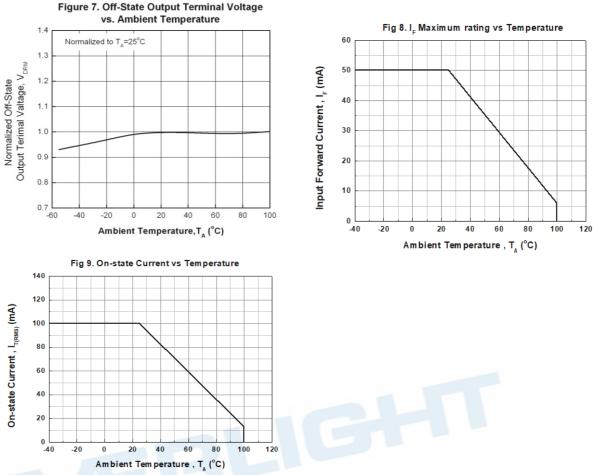
^{*3.} This is static dv/dt. See Figure 10 for test circuit. Commutating dv/dt is a function of the load-driving thyristor(s) only.

^{*4.} All devices are guaranteed to trigger at an IF value over than max IFT



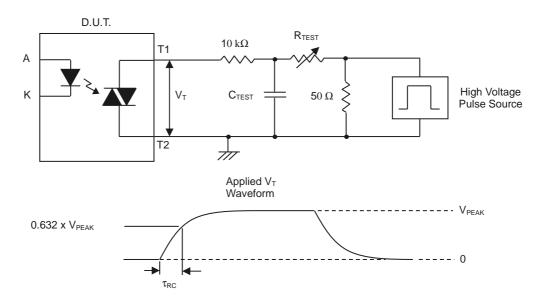
Typical Electro-Optical Characteristics Curves





Note: The graphs shown in this datasheet are representing typical data only and do not show guaranteed values

Figure 10. Static dv/dt Test Circuit & Waveform





Measurement Method

The high voltage pulse is set to the required V_{PEAK} value and applied to the D.U.T. output side through the RC circuit above. LED current is not applied. The waveform V_T is monitored using a x100 scope probe. By varying R_{TEST} , the dv/dt (slope) is increased, until the D.U.T. is observed to trigger (waveform collapses). The dv/dt is then decreased until the D.U.T. stops triggering. At this point, τ_{RC} is recorded and the dv/dt calculated.

$$dv/dt = \frac{0.632 \text{ x V}_{PEAK}}{\tau_{RC}}$$

Order Information

Part Number

EL301XY(Z)-V or EL302XY(Z)-V or EL305XY(Z)-V

Notes

X = Part No. for EL301x (0, 1 or 2).

X = Part No. for EL302x (0,1, 2 or 3)

X = Part No. for EL305x (1, 2 or 3)

Y = Lead form option (S, S1, M or none)

Z = Tape and reel option (TA, TB or none).

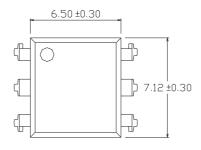
V = VDE safety approved (optional)

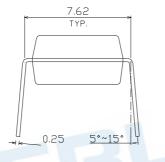
| Option | Description | Packing quantity |
|---------|---------------------------------------------------------------|---------------------|
| None | Standard DIP-6 | 65 units per tube |
| М | Wide lead bend (0.4 inch spacing) | 65 units per tube |
| S | Surface mount lead form | 65 units per tube |
| S (TA) | Surface mount lead form + TA tape & reel option | 1000 units per reel |
| S (TB) | Surface mount lead form + TB tape & reel option | 1000 units per reel |
| S1 (TA) | Surface mount lead form (low profile) + TA tape & reel option | 1000 units per reel |
| S1 (TB) | Surface mount lead form (low profile) + TB tape & reel option | 1000 units per reel |

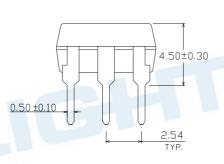


Package Dimension (Dimensions in mm)

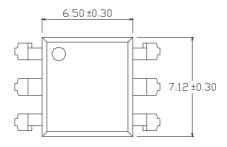
Standard DIP Type

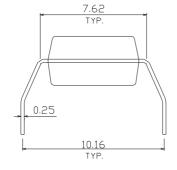


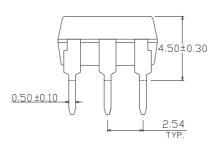




Option M Type

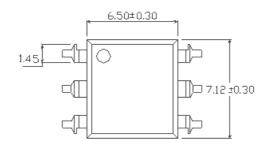


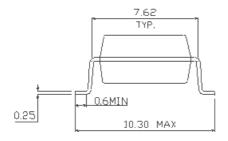


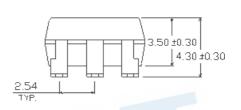




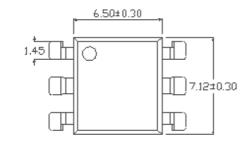
Option S Type

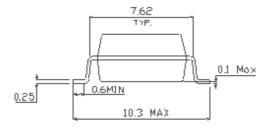


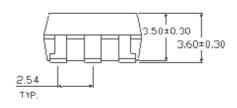




Option S1 Type

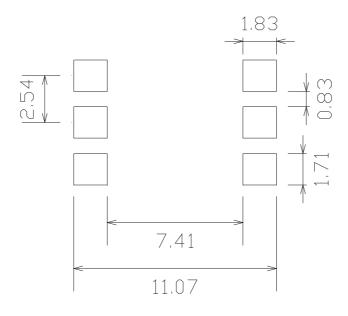








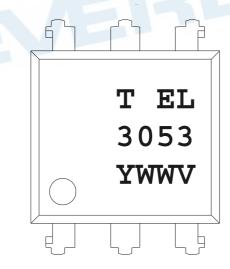
Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Device Marking



Notes

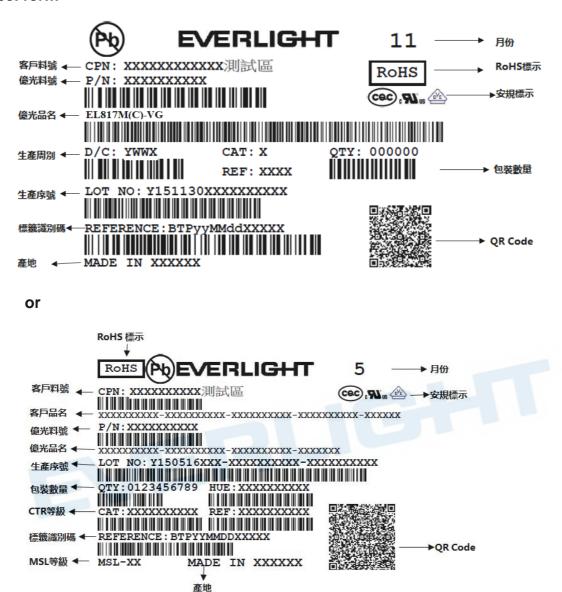
No code : made in China

T: made in Taiwan

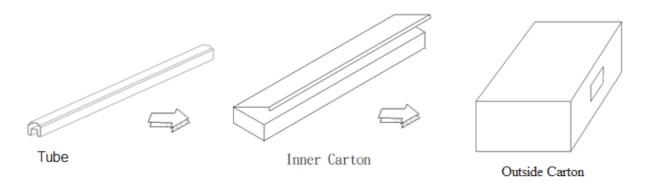
EL denotes EVERLIGHT
3053 denotes Device Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE (optional)



Label form

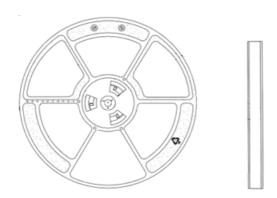


TUBE Dimension

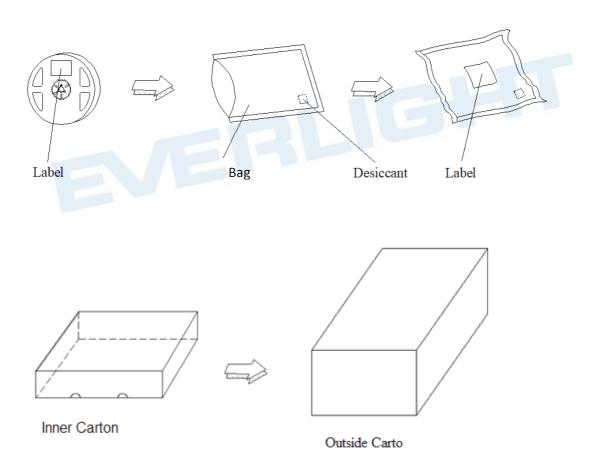




Reel Dimension

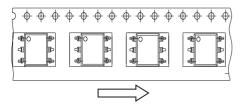


Moisture Resistant Packaging



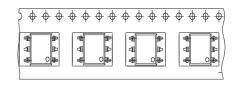
Tape & Reel Packing Specifications

Option TA



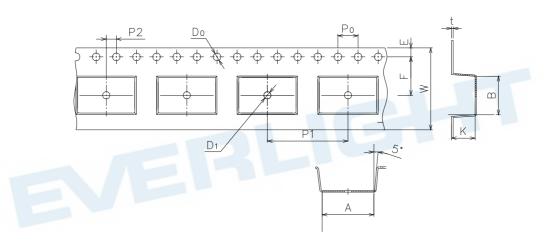
Direction of feed from reel

Option TB



Direction of feed from reel

Tape dimensions



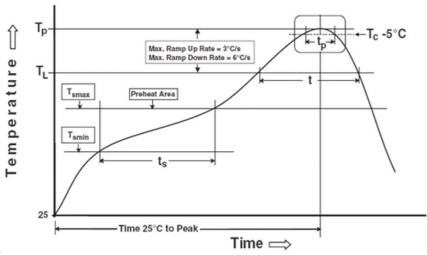
| Dimension No. | Α | В | Do | D1 | E | F |
|----------------|----------|---------|---------|---------|----------|---------|
| Dimension (mm) | 10.8±0.1 | 7.5±0.1 | 1.5±0.1 | 1.5±0.1 | 1.75±0.1 | 7.5±0.1 |
| Dimension No. | Ро | P1 | P2 | t | W | K |
| | | | | | | |



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Notes Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin}) 150 °C

Temperature max (T_{smax}) 200 °C

Time $(T_{smin} \text{ to } T_{smax})$ (ts) 60-120 seconds

Average ramp-up rate (T_{smax} to T_p)

3 °C/second max

Other

Liquidus Temperature (T_L) 217 °C
Time above Liquidus Temperature (t_L) 60-100 s

Time above Liquidus Temperature (t L) 60-100 sec

Peak Temperature (T_P) 260°C Time within 5 °C of Actual Peak Temperature: T_P - 5°C 30 s

Ramp- Down Rate from Peak Temperature 6°C /second max.

tamp- bown Rate from Peak Temperature 6 C/second ma.

Time 25°C to peak temperature 8 minutes max. Reflow times 3 times

40



Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5°C to 35°C and 20 % to 60 %,respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.





DISCLAIMER

- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 4. These specification sheets include materials protected under copyright of EVERLIGHT. Reproduction in any form is prohibited without the specific consent of EVERLIGHT.
- 5. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.
- 6. Statements regarding the suitability of products for certain types of applications are based on Everlight's knowledge of typical requirements that are often placed on Everlight products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Everlight's terms and conditions of purchase, including but not limited to the warranty expressed therein.